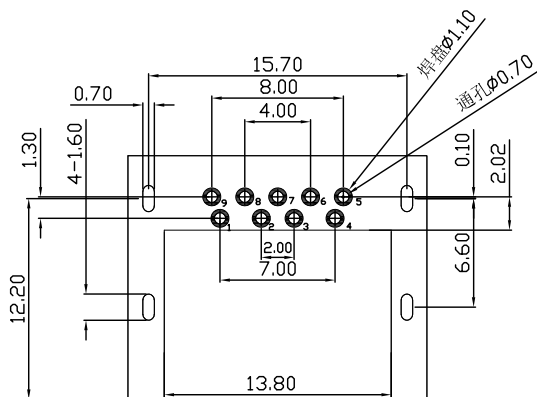
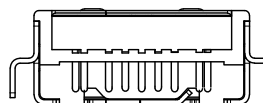
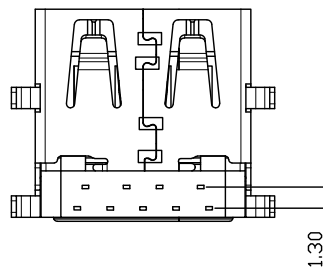
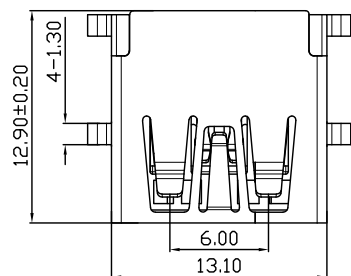
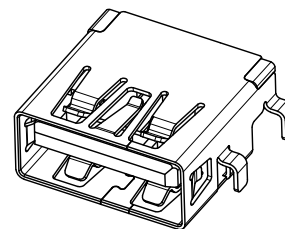
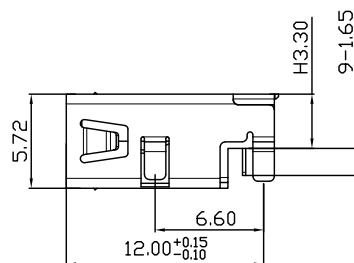
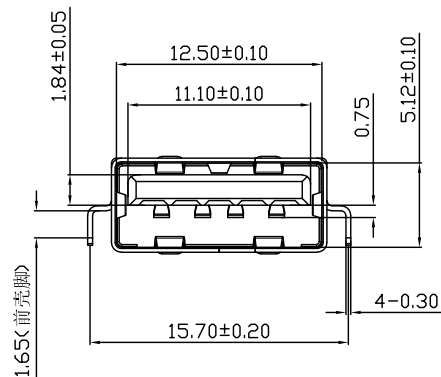




TOLERANCE: ± 0.05 , THICKNESS: 1.2 mm
RECOMMENDED PCB LAYOUT

5	STDA_SSRX-	9	STDA_SSTX+
4	GND	8	STDA_SSTX-
3	D+	7	GND_DRAIN
2	D-	6	STDA_SSRX+
1	VBUS		
PIN#	SLGNAL NAME	PIN#	SLGNAL NAME

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: 铜合金
- 1.3 CONTACT 5~9PIN: 铜合金
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

2.1 CONTACT:

CONTACT AREA: GOLD PLATING.

SOLDER AREA: 100u" Min MATTE TIN PLATING.

UNDER PLATE: 50u" Min NICKEL PLATING.

2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

3.1 ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 30mΩ MAXIMUM

CONTACT CURRENT RATING: 3A

DIELECTRIC WITHSTANDING VOLTAGE: 500 V

R.M.S.

INSULATION RESISTANCE: 1000 MEGOHMS

MIN

OPERATING TEMPERATURE: -25~C ~

+85°C

3.2 MECHANICAL:

Before lifespan: insertion force 8-25N;
pull-out force

10-25N.

After lifespan: 6N Min.

4. PART MUST COMPLY ROHS SPECIFICATION

5. SOLDER RESISTANCE TEMPERATURE:

260 $\pm$ 5°C FOR 3 MINUTES.

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	铜合金	Overall nickel plating 50u" ~ 100u", contact area gold plating 1U", welding leg tin plating 100u"
1	HSG	LCP+30%GF	BLUE UL94V-0
NO.	PART NAME	MATERIAL	DESCRIPTION



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X.' $\pm 2'$ X.X' $\pm 0.5'$	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB 3.0 AF 沉板DIP 板上3.3 无卷边
UNIT: mm [inch]	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW181-USBA09-330B
SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.
			DRAW NO: HYC-2604281457
			SHEET NO. 1 OF 1